

## SNx4HCT04 六路反相器

### 1 特性

- 4.5V 至 5.5V 的工作电压范围
- 输出可驱动多达 10 个 LSTTL 负载
- 低功耗， $I_{CC}$  最大值为 20  $\mu$  A
- $t_{pd}$  典型值 = 13ns
- $\pm 4$ mA 输出驱动 (在 5V 时)
- 低输入电流，最大值 1  $\mu$  A
- 输入兼容 TTL 电压

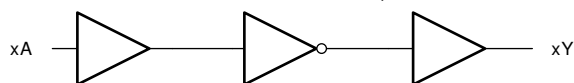
### 2 说明

这些器件包含六个独立的反相器。它们以正逻辑执行布尔函数  $Y = A$ 。

#### 器件信息<sup>(1)</sup>

器件型号	封装	封装尺寸 (标称值)
SN74HCT04PW	TSSOP (14)	5.00mm × 4.40mm
SN74HCT04D	SOIC (14)	8.65mm × 3.90mm
SN74HCT04N	PDIP (14)	19.31mm × 6.35mm
SN74HCT04NSR	SO (14)	10.20mm × 5.30mm
SNJ54HCT04FK	LCCC (20)	8.89mm × 8.89mm
SNJ54HCT04J	CDIP (14)	19.55mm × 6.71mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



功能方框图



## Table of Contents

<b>1 特性</b> .....	1	7.2 Functional Block Diagram.....	7
<b>2 说明</b> .....	1	7.3 Device Functional Modes.....	7
<b>3 Revision History</b> .....	2	<b>8 Power Supply Recommendations</b> .....	8
<b>4 Pin Configuration and Functions</b> .....	3	<b>9 Layout</b> .....	8
<b>5 Specifications</b> .....	4	9.1 Layout Guidelines.....	8
5.1 Absolute Maximum Ratings.....	4	<b>10 Device and Documentation Support</b> .....	9
5.2 Recommended Operating Conditions <sup>(1)</sup> .....	4	10.1 Documentation Support.....	9
5.3 Thermal Information.....	4	10.2 接收文档更新通知.....	9
5.4 Electrical Characteristics.....	5	10.3 支持资源.....	9
5.5 Switching Characteristics.....	5	10.4 Trademarks.....	9
5.6 Operating Characteristics.....	5	10.5 Electrostatic Discharge Caution.....	9
<b>6 Parameter Measurement Information</b> .....	6	10.6 术语表.....	9
<b>7 Detailed Description</b> .....	7	<b>11 Mechanical, Packaging, and Orderable Information</b> .....	9
7.1 Overview.....	7		

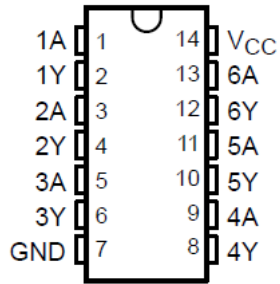
### 3 Revision History

注：以前版本的页码可能与当前版本的页码不同

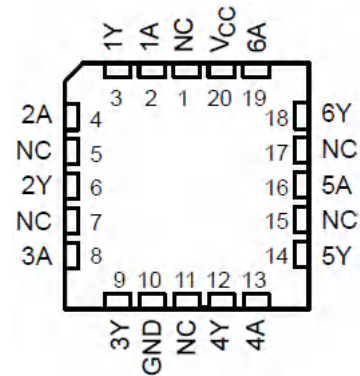
<b>Changes from Revision E (February 2022) to Revision F (October 2022)</b>	<b>Page</b>
• Increased R <sup>θ</sup> JA for packages: D (86 to 138.7); N (80 to 62.7); NS (76 to 90.9); PW (113 to 117.6).....	4

<b>Changes from Revision D (July 2003) to Revision E (February 2022)</b>	<b>Page</b>
• 更新了整个文档中的编号、格式、表格、图和交叉参考，以反映现代数据表标准.....	1

## 4 Pin Configuration and Functions



**J, D, N, NS, or PW Package**  
**14-Pin CDIP, SOIC, PDIP, SO, or TSSOP**  
**Top View**



**FK Package**  
**20-Pin LCCC**  
**Top View**

## 5 Specifications

### 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	-0.5	7	V
I <sub>IK</sub>	Input clamp current <sup>(2)</sup>	(V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>CC</sub> )		±20 mA
I <sub>OK</sub>	Output clamp current <sup>(2)</sup>	(V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )		±20 mA
I <sub>O</sub>	Continuous output current	(V <sub>O</sub> = 0 to V <sub>CC</sub> )		±25 mA
V <sub>CC</sub> or GND	Continuous current through V <sub>CC</sub> or GND			±50 mA
T <sub>J</sub>	Junction temperature			150 °C
T <sub>stg</sub>	Storage temperature	-65	150	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 5.2 Recommended Operating Conditions<sup>(1)</sup>

		SN54HCT04			SN74HCT04			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V		2	2		V	
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V		0.8		0.8	V	
V <sub>I</sub>	Input voltage	0	V <sub>CC</sub>		0	V <sub>CC</sub>		V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>		0	V <sub>CC</sub>		V
Δt / Δv	Input transition rise/fall time	500		500		500	ns	
T <sub>A</sub>	Operating free-air temperature	-55	125		-40	85		°C

- (1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

### 5.3 Thermal Information

THERMAL METRIC		D (SOIC)	N (PDIP)	NS (SO)	PW (TSSOP)	UNIT
		14 PINS	14 PINS	14 PINS	14 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance <sup>(1)</sup>	138.7	62.7	90.9	117.6	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	93.8	50.5	48.5	46.9	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	94.7	42.5	51.5	60.6	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	49.1	30.1	15.9	5.6	°C/W
ψ <sub>JB</sub>	Junction-to-case (bottom) thermal resistance	94.3	42.2	51	60	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	N/A	N/A	N/A	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics](#) application report.

## 5.4 Electrical Characteristics

PARAMETER		TEST CONDITIONS <sup>(1)</sup>	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C			SN54HCT00		SN74HCT00		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	High-level output voltage	I <sub>OH</sub> = - 20 μA	4.5	4.4	4.499		4.4		4.4	V	
		I <sub>OH</sub> = - 4 mA		3.98	4.3		3.7		3.84		
V <sub>OL</sub>	Low-level output voltage	I <sub>OL</sub> = 20 μA	5.5		0.001	0.1		0.1		0.1	V
		I <sub>OL</sub> = 4 mA			0.17	0.26		0.4		0.33	
I <sub>I</sub>	Input hold current	V <sub>I</sub> = V <sub>CC</sub> or 0	5.5		±0.1	±100		±1000		±1000	nA
I <sub>CC</sub>	Supply current	V <sub>I</sub> = V <sub>CC</sub> or 0. I <sub>O</sub> = 0	5.5			2		40		20	μA
Δ I <sub>CC</sub> (2)	Supply-current change	One input at 0.5V or 2.4 V, Other inputs at 0 or V <sub>CC</sub>	5.5		1.4	2.4		3		2.9	mA
C <sub>i</sub>	Input capacitance		4.5 to 5.5		3	10		10		10	pF

(1) V<sub>I</sub> = V<sub>IH</sub> or V<sub>IL</sub>, unless otherwise noted.

(2) This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

## 5.5 Switching Characteristics

C<sub>L</sub> = 50 pF. See [Parameter Measurement Information](#)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C			SN54HCT04		SN74HCT04		UNIT
					MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	Propagation delay	A or B	Y	4.5		14	20		30		25	ns
				5.5		13	18		27		23	
t <sub>t</sub>	Transition time		Y	4.5		9	15		22		19	ns
				5.5		8	14		20		17	

## 5.6 Operating Characteristics

T<sub>A</sub> = 25°C

		Test Conditions	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load	20	pF

## 6 Parameter Measurement Information

Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_f < 6 \text{ ns}$ .

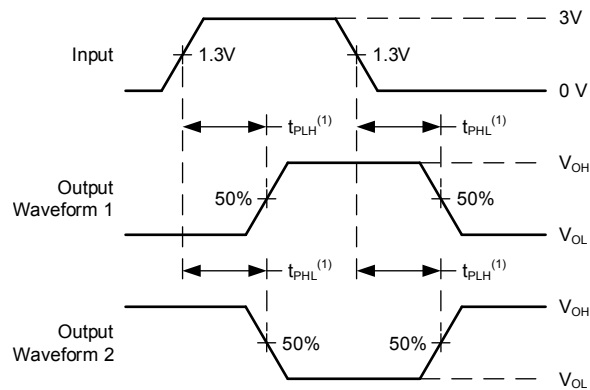
For clock inputs,  $f_{max}$  is measured when the input duty cycle is 50%.

The outputs are measured one at a time with one input transition per measurement.



(1)  $C_L$  includes probe and test-fixture capacitance.

**图 6-1. Load Circuit for Push-Pull Outputs**



(1) The greater between  $t_{PLH}$  and  $t_{PHL}$  is the same as  $t_{pd}$ .

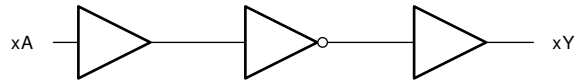
**图 6-2. Voltage Waveforms, Propagation Delays for TTL-Compatible Inputs**

## 7 Detailed Description

### 7.1 Overview

These devices contain six independent inverters. They perform the Boolean function  $Y = \bar{A}$  in positive logic.

### 7.2 Functional Block Diagram



### 7.3 Device Functional Modes

表 7-1. Function Table  
(each inverter)

Input A	Output Y
H	L
L	H

## 8 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each  $V_{CC}$  terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- $\mu$ F capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- $\mu$ F and 1- $\mu$ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

## 9 Layout

### 9.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or  $V_{CC}$ , whichever makes more sense for the logic function or is more convenient.



## 10 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 10.1 Documentation Support

#### 10.1.1 Related Documentation

### 10.2 接收文档更新通知

要接收文档更新通知，请导航至 [ti.com](http://ti.com) 上的器件产品文件夹。点击 [订阅更新](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

### 10.3 支持资源

TI E2E™ [支持论坛](#) 是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [《使用条款》](#)。

### 10.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

所有商标均为其各自所有者的财产。

### 10.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 10.6 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

## 11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">5962-89747012A</a>	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 89747012A SNJ54HCT 04FK
<a href="#">5962-8974701CA</a>	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8974701CA SNJ54HCT04J
<a href="#">5962-8974701VCA</a>	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8974701VC A SNV54HCT04J
<a href="#">5962-8974701VDA</a>	Active	Production	CFP (W)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8974701VD A SNV54HCT04W
<a href="#">JM38510/65751BCA</a>	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 65751BCA
<a href="#">SN54HCT04J</a>	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HCT04J
<a href="#">SN74HCT04D</a>	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	-40 to 85	HCT04
<a href="#">SN74HCT04DR</a>	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 85	HCT04
<a href="#">SN74HCT04DRE4</a>	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT04
<a href="#">SN74HCT04DRG4</a>	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT04
<a href="#">SN74HCT04DT</a>	Obsolete	Production	SOIC (D)   14	-	-	Call TI	Call TI	-40 to 85	HCT04
<a href="#">SN74HCT04N</a>	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HCT04N
<a href="#">SN74HCT04NSR</a>	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU   NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT04
<a href="#">SN74HCT04PW</a>	Obsolete	Production	TSSOP (PW)   14	-	-	Call TI	Call TI	-40 to 85	HT04
<a href="#">SN74HCT04PWR</a>	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 85	HT04
<a href="#">SN74HCT04PWT</a>	Obsolete	Production	TSSOP (PW)   14	-	-	Call TI	Call TI	-40 to 85	HT04
<a href="#">SNJ54HCT04FK</a>	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 89747012A SNJ54HCT 04FK
<a href="#">SNJ54HCT04J</a>	Active	Production	CDIP (J)   14	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8974701CA SNJ54HCT04J

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN54HCT04, SN54HCT04-SP, SN74HCT04 :**

- Catalog : [SN74HCT04](#), [SN54HCT04](#)
- Enhanced Product : [SN74HCT04-EP](#), [SN74HCT04-EP](#)
- Military : [SN54HCT04](#)
- Space : [SN54HCT04-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HCT04DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HCT04DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HCT04DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HCT04NSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74HCT04NSR	SOP	NS	14	2000	330.0	16.4	8.45	10.55	2.5	12.0	16.2	Q1
SN74HCT04PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HCT04PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HCT04PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.3	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HCT04DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74HCT04DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74HCT04DRG4	SOIC	D	14	2500	353.0	353.0	32.0
SN74HCT04NSR	SOP	NS	14	2000	356.0	356.0	35.0
SN74HCT04NSR	SOP	NS	14	2000	356.0	356.0	35.0
SN74HCT04PWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74HCT04PWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74HCT04PWR	TSSOP	PW	14	2000	367.0	367.0	35.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-89747012A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-8974701VDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74HCT04N	N	PDIP	14	25	506	13.97	11230	4.32
SN74HCT04N	N	PDIP	14	25	506	13.97	11230	4.32
SN74HCT04NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74HCT04NE4	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54HCT04FK	FK	LCCC	20	55	506.98	12.06	2030	NA



# D0014A

# PACKAGE OUTLINE

## SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

### NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.



# EXAMPLE BOARD LAYOUT

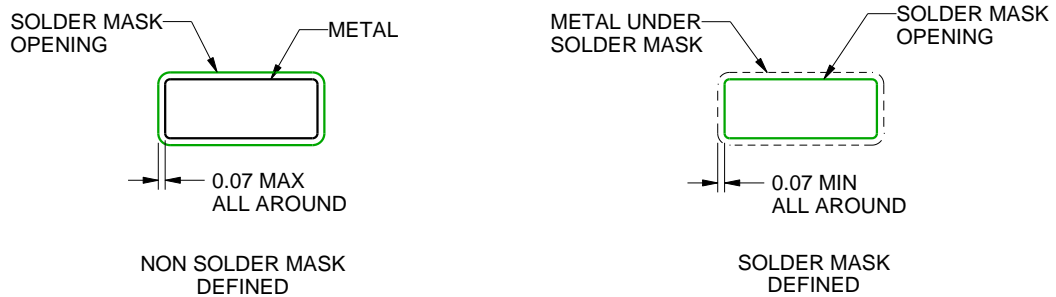
D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14

## GENERIC PACKAGE VIEW

**FK 20**

**LCCC - 2.03 mm max height**

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4229370VA\

J 14

**GENERIC PACKAGE VIEW**  
**CDIP - 5.08 mm max height**  
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G

J0014A



# PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

**NOTES:**

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

# EXAMPLE BOARD LAYOUT

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X



4214771/A 05/2017



N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

PW0014A



**PACKAGE OUTLINE**  
**TSSOP - 1.2 mm max height**

SMALL OUTLINE PACKAGE



4220202/B 12/2023

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220202/B 12/2023

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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